EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L7	1285047	(undulat$6 wav$4 rippl$5 wavelike sinous$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/20 07:44
L8	355126	"1" with (lead leadframe (lead adj frame))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/20 07:19
L9	26118	7 with (lead leadframe (lead adj frame))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/20 07:44
L10	2928	(semiconductor ic chip die dice (integrated adj circuit) flipchip (flip adj chip)) same 9	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/20 07:44
L11	713	(substrate carrier board pcb) same 10	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/20 07:43
L12	98205	(doubleside double$5 dual) with (substrate carrier board pcb)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/20 07:43
L13	2138	12 with (lead leadframe (lead adj frame))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/20 07:44
L14	1063	(semiconductor ic chip die dice (integrated adj circuit) flipchip (flip adj chip)) same 13	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/20 07:44

L15	120	(undulat$6 wav$4 rippl$5 wavelike sinous$4) and 14	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/20 07:44